

MC74HC1G32

2-Input OR Gate

The MC74HC1G32 is a high speed CMOS 2-input OR gate fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent LSTTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The MC74HC1G32 output drive current is 1/2 compared to MC74HC series.

- High Speed: $t_{PD} = 7\text{ns}$ (Typ) at $V_{CC} = 5\text{V}$
- Low Power Dissipation: $I_{CC} = 1\mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- High Noise Immunity
- Balanced Propagation Delays ($t_{pLH} = t_{pHL}$)
- Output Drive Capability: 5 LSTTL
- Symmetrical Output Impedance ($I_{OH} = I_{OL} = 2\text{mA}$)
- ESD Performance: HBM > 2000V; MM > 200V

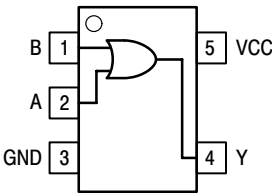


Figure 1. Pinout (Top View)

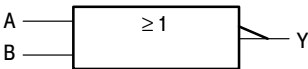


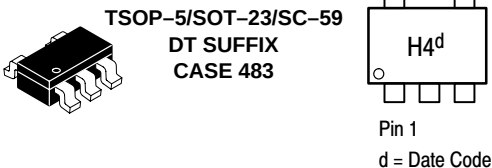
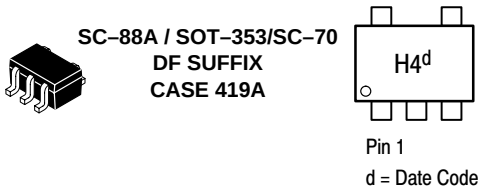
Figure 2. Logic Symbol



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MARKING DIAGRAMS



PIN ASSIGNMENT

PIN ASSIGNMENT	
1	IN B
2	IN A
3	GND
4	OUT Y
5	VCC

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	H

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MAXIMUM RATINGS*

Characteristics	Symbol	Value	Unit
DC Supply Voltage	V_{CC}	-0.5 to +7.0	V
DC Input Voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current ($V_{OUT} < GND$; $V_{OUT} > V_{CC}$)	I_{OK}	± 20	mA
DC Output Current, per Pin	I_{OUT}	± 12.5	mA
DC Supply Current, V_{CC} and GND	I_{CC}	± 25	mA
Power dissipation in still air	P_D	200 450	mW
Lead temperature, 1 mm from case for 10 s	T_L	260	°C
Storage temperature	T_{stg}	-65 to +150	°C

* Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

† Derating — SC-88A Package: -3 mW/°C from 65° to 125°C
— TSOP5 Package: -6 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Characteristics	Symbol	Min	Max	Unit
DC Supply Voltage	V_{CC}	2.0	6.0	V
DC Input Voltage	V_{IN}	0.0	V_{CC}	V
DC Output Voltage	V_{OUT}	0.0	V_{CC}	V
Operating Temperature Range	T_A	-55	+125	°C
Input Rise and Fall Time	t_r, t_f	0	1000	ns
		0	600	
		0	500	
		0	400	

The θ_{JA} of the package is equal to 1/Derating. Higher junction temperatures may affect the expected lifetime of the device per the table and figure below.

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

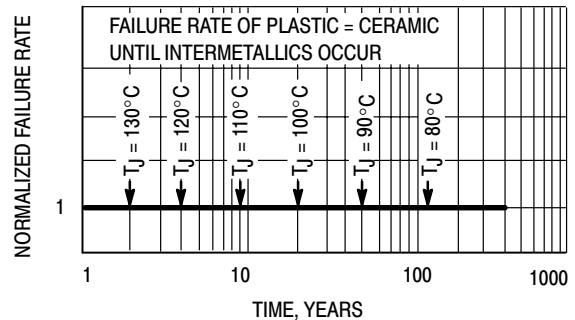


Figure 3. Failure Rate vs. Time Junction Temperature

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DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CC} (V)	T _A = 25°C			T _A ≤ 85°C		T _A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	Minimum High-Level Input Voltage		2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.20			1.5 2.1 3.15 4.20		1.5 2.1 3.15 4.20		V
V _{IL}	Maximum Low-Level Input Voltage		2.0 3.0 4.5 6.0			0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80	V
V _{OH}	Minimum High-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	V _{IN} = V _{IH} or V _{IL} I _{OH} = -20μA	2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0		1.9 2.9 4.4 5.9		1.9 2.9 4.4 5.9		V
		V _{IN} = V _{IH} or V _{IL} I _{OH} = -2mA I _{OH} = -2.6mA	4.5 6.0	4.18 5.68	4.31 5.80		4.13 5.63		4.08 5.58		V
V _{OL}	Maximum Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	V _{IN} = V _{IH} or V _{IL} I _{OL} = 20μA	2.0 3.0 4.5 6.0		0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1	V
		V _{IN} = V _{IH} or V _{IL} I _{OL} = 2mA I _{OL} = 2.6mA	4.5 6.0		0.17 0.18	0.26 0.26		0.33 0.33		0.40 0.40	V
I _{IN}	Maximum Input Leakage Current	V _{IN} = 6.0V or GND	0 to 6.0			±0.1		±1.0		±1.0	μA
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND	6.0			1.0		10		40	μA

AC ELECTRICAL CHARACTERISTICS (C_{load} = 50 pF, Input t_r = t_f = 6.0ns)

Symbol	Parameter	Test Conditions	T _A = 25°C			T _A ≤ 85°C		T _A ≤ 125°C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input A or B to Y	V _{CC} = 5.0V C _L = 15 pF		7.0	15		20		25	ns
		V _{CC} = 2.0V C _L = 50 pF V _{CC} = 3.0V V _{CC} = 4.5V V _{CC} = 6.0V		48 24 12 9.0	100 40 20 17		125 50 25 21		155 90 35 26	
t _{TLH} , t _{THL}	Output Transition Time	V _{CC} = 5.0V C _L = 15 pF		5.0	10		15		20	ns
		V _{CC} = 2.0V C _L = 50 pF V _{CC} = 3.0V V _{CC} = 4.5V V _{CC} = 6.0V		50 22 14 12	125 35 25 21		155 45 31 26		200 60 38 32	
C _{IN}	Maximum Input Capacitance			5	10		10		10	pF

C _{PD}	Power Dissipation Capacitance (Note 1.)	Typical @ 25°C, V _{CC} = 5.0V	pF
		10	

1. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

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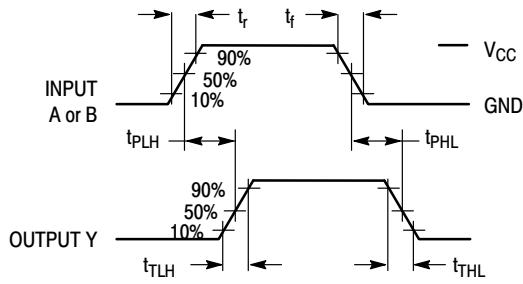


Figure 4. Switching Waveforms

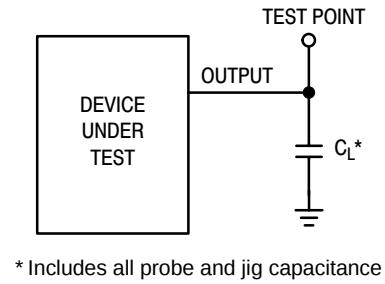


Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

Device Order Number	Device Nomenclature						Package Type (Name/SOT#/ Common Name)	Tape and Reel Size
	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix		
MC74HC1G32DFT2	MC	74	HC1G	32	DF	T2	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74HC1G32DFT4	MC	74	HC1G	32	DF	T4	SC-88A / SOT-353 / SC-70	330 mm (13") 10000 Unit
MC74HC1G32DTT1	MC	74	HC1G	32	DT	T1	TSOPS / SOT-23 / SC-59	178 mm (7") 3000 Unit
MC74HC1G32DTT3	MC	74	HC1G	32	DT	T3	TSOPS / SOT-23 / SC-59	330 mm (13") 10000 Unit

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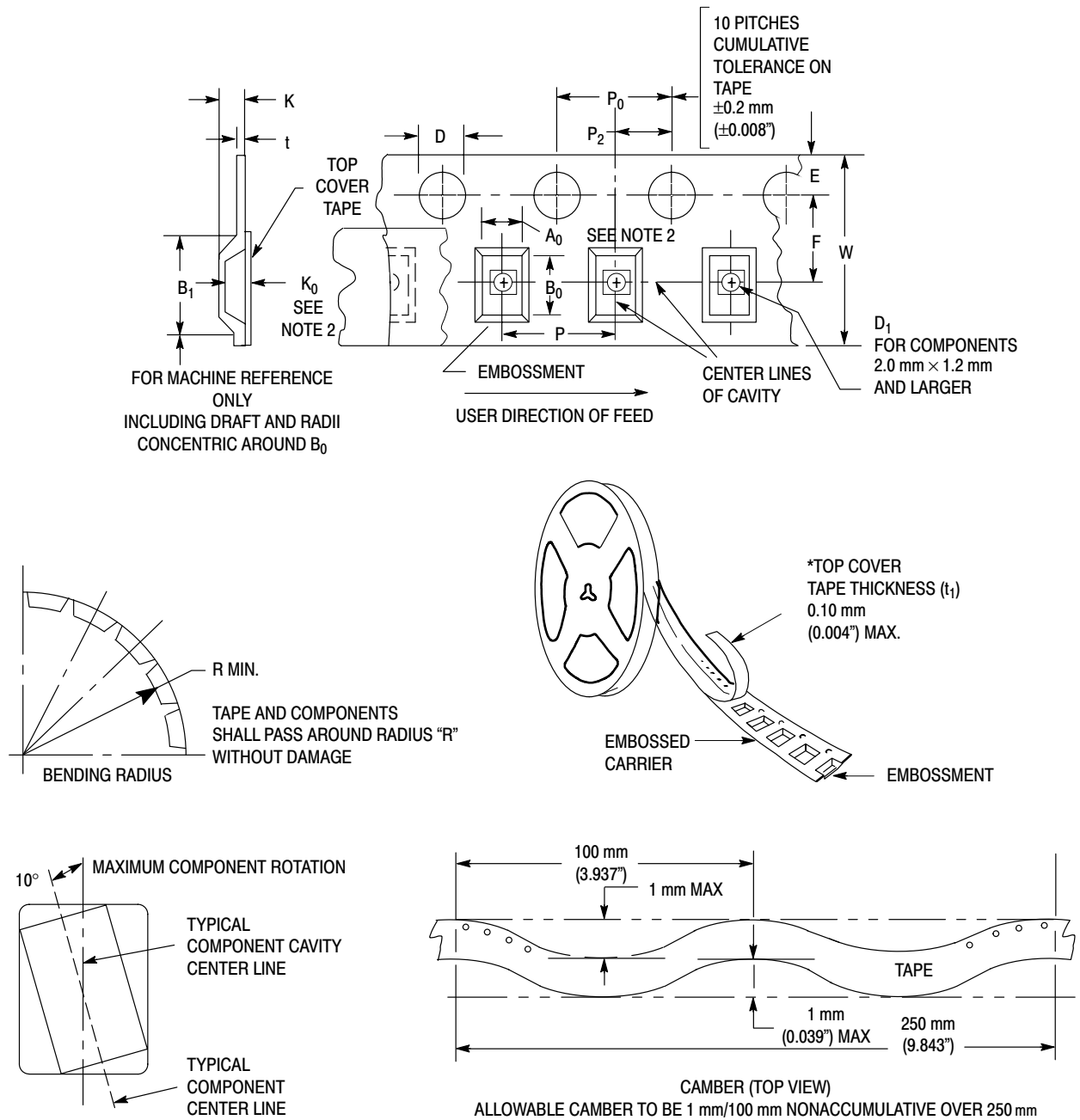


Figure 6. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 1 and 2)

Tape Size	B_1 Max	D	D_1	E	F	K	P	P_0	P_2	R	T	W
8 mm	4.35 mm (0.171")	1.5 +0.1/-0.0 mm (0.059 +0.004/-0.0")	1.0 mm Min (0.039")	1.75 ± 0.1 mm (0.069 ± 0.004 ")	3.5 ± 0.5 mm (1.38 ± 0.002 ")	2.4 mm (0.094")	4.0 ± 0.10 mm (0.157 ± 0.004 ")	4.0 ± 0.1 mm (0.156 ± 0.004 ")	2.0 ± 0.1 mm (0.079 ± 0.002 ")	25 mm (0.98")	0.3 ± 0.05 mm (0.01 +0.0038/-0.0002")	8.0 ± 0.3 mm (0.315 ± 0.012 ")

- Metric Dimensions Govern—English are in parentheses for reference only.
- A_0 , B_0 , and K_0 are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

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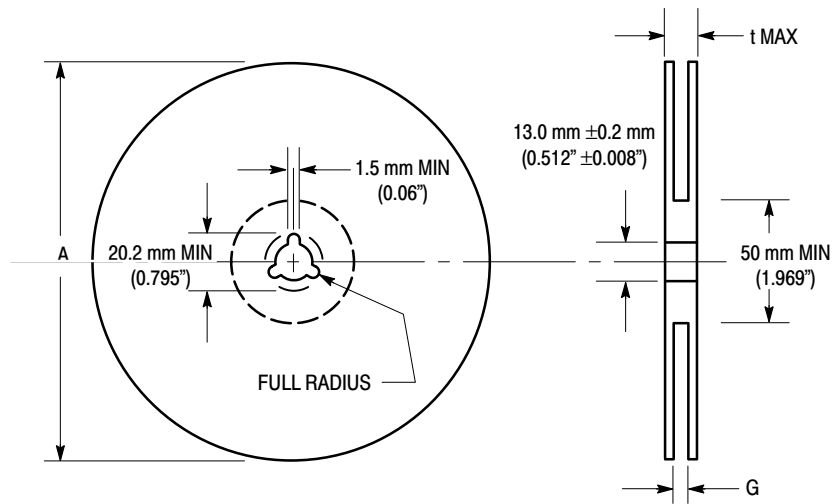


Figure 7. Reel Dimensions

REEL DIMENSIONS

Tape Size	T&R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")
8 mm	T3, T4	330 mm (13")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")

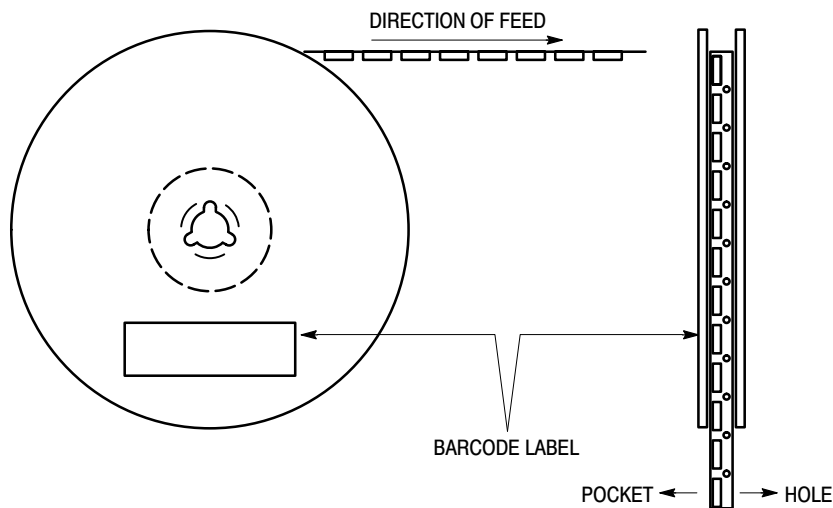


Figure 8. Reel Winding Direction

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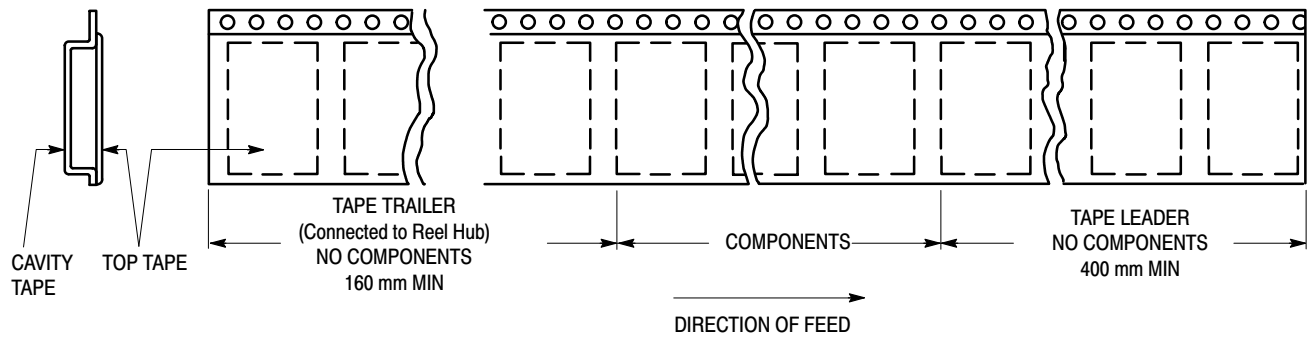


Figure 9. Tape Ends for Finished Goods

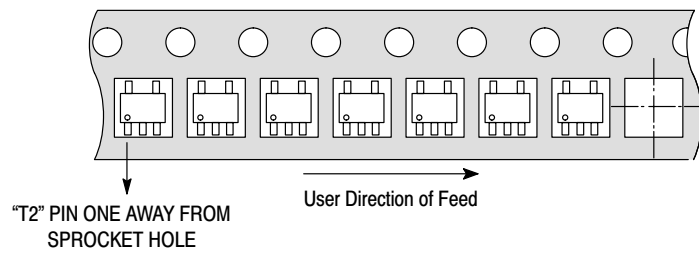


Figure 10. DFT2 AND DFT4 (SC88A) Reel Configuration/Orientation

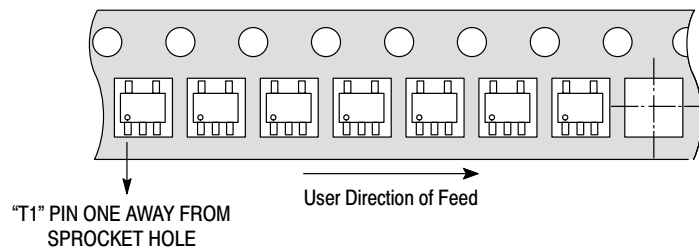
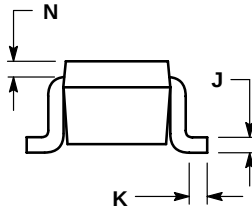
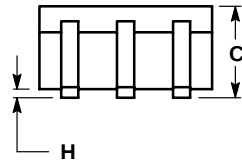
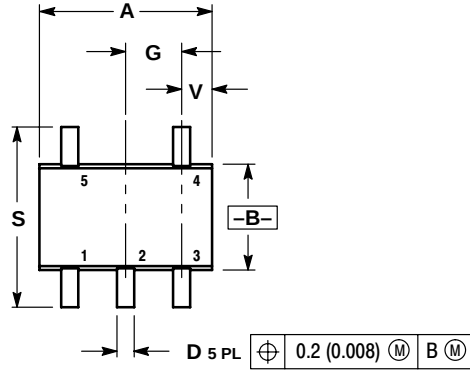


Figure 11. DTT1 AND DTT3 (TSOP5) Reel Configuration/Orientation

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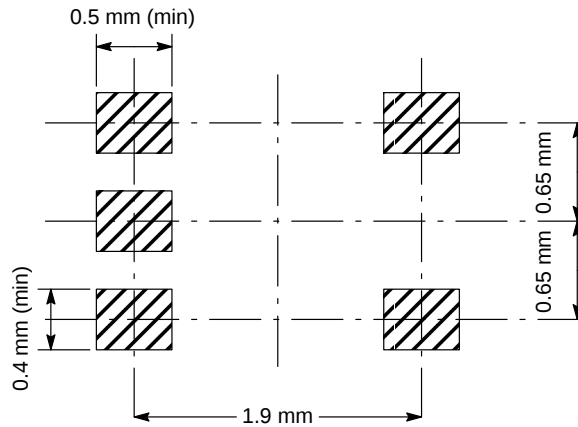
PACKAGE DIMENSIONS

SC-88A / SOT-353 / SC-70
 DF SUFFIX
 5-LEAD PACKAGE
 CASE 419A-01
 ISSUE B



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20
V	0.012	0.016	0.30	0.40



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PACKAGE DIMENSIONS

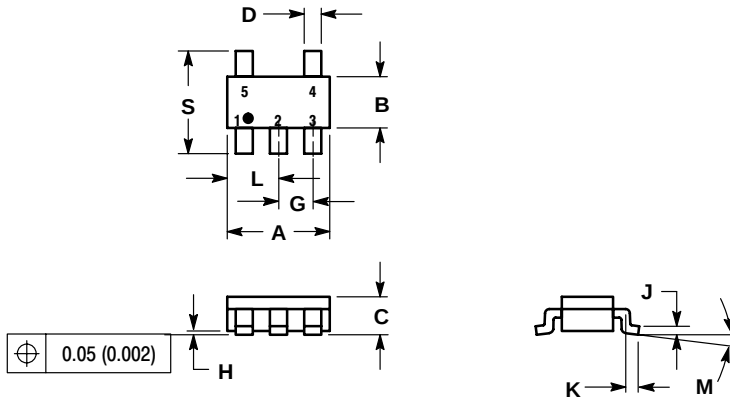
TSOP-5/SOT-23/SC-59

DT SUFFIX

5-LEAD PACKAGE

CASE 483-01

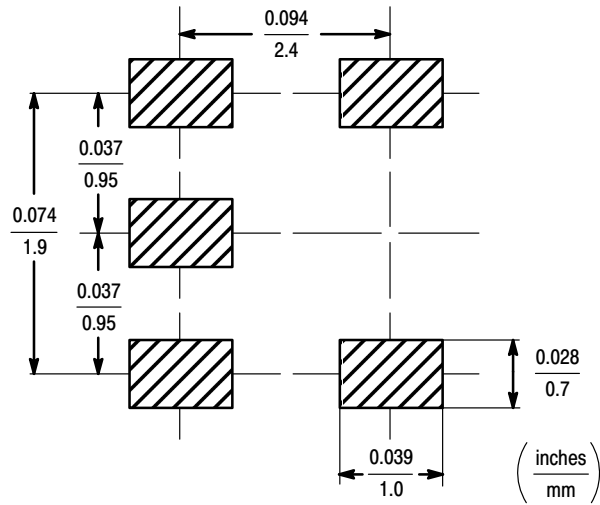
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.1142	0.1220
B	1.30	1.70	0.0512	0.0669
C	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.00	0.0335	0.0413
H	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0°	10°	0°	10°
S	2.50	3.00	0.0985	0.1181



Notes

Notes

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